

**SEMICONDUCTOR ENCAPSULATING EPOXY RESIN COMPOSITIONS
AND SEMICONDUCTOR DEVICES ENCAPSULATED THEREWITH**

ABSTRACT

An epoxy resin composition comprising (A) 20-80 parts
5 by weight of an epoxy resin, (B) 20-80 parts by weight of a
curing agent, (C) 0.1-50 parts by weight of a phosphorus-
containing flame retardant, and (D) 200-1,200 parts by
weight of an inorganic filler cures into products having
improved high-temperature exposure resistance, flame
10 retardancy, and reflow cracking resistance. The composition
eliminates blending of antimony trioxide and brominated
compounds and is useful in encapsulating semiconductor
devices for imparting high-temperature reliability.